



Material Content Data Sheet



Sales Product Name	TLE8386-2EL			Issued		16. January 2020		
MA#	MA000971486							
Package	PG-SSOP-14-3			Weight*		83.39 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.378	2.85	2.85	28520	28520
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		103	
	non noble metal	zinc	7440-66-6	0.034	0.04		413	
	non noble metal	iron	7439-89-6	0.689	0.83		8263	
	non noble metal	copper	7440-50-8	27.978	33.55	34.43	335522	344301
wire	noble metal	gold	7440-57-5	0.211	0.25	0.25	2526	2526
encapsulation	organic material	carbon black	1333-86-4	0.098	0.12		1175	
	plastics	epoxy resin	-	4.509	5.41		54069	
	inorganic material	silicondioxide	60676-86-0	44.399	53.25	58.78	532460	587704
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11706	11706
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9206	9206
glue	plastics	epoxy resin	-	0.334	0.40		4009	
	noble metal	silver	7440-22-4	1.003	1.20	1.60	12028	16037
*deviation	< 10%	Sum in total:			100.00		1000000	

Important Remarks:

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2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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